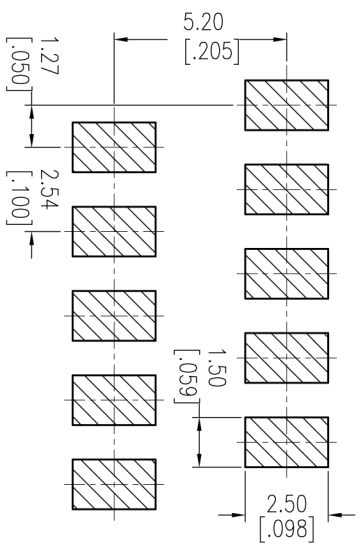
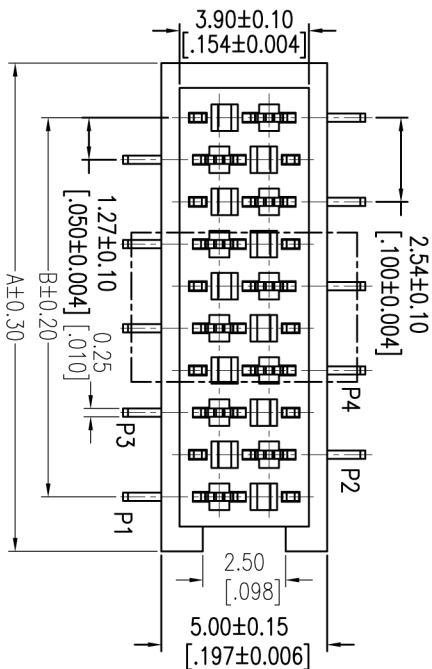


# HSHF

Recommended P.C.B Layout(Top Side)  
(PCB BOARD TOLERANCE±0.05)

**NOTES:**

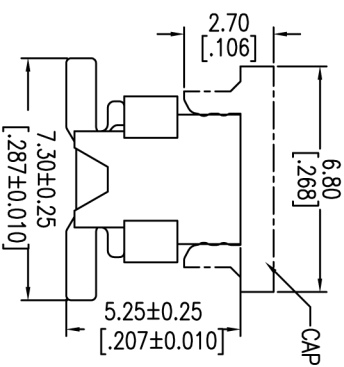
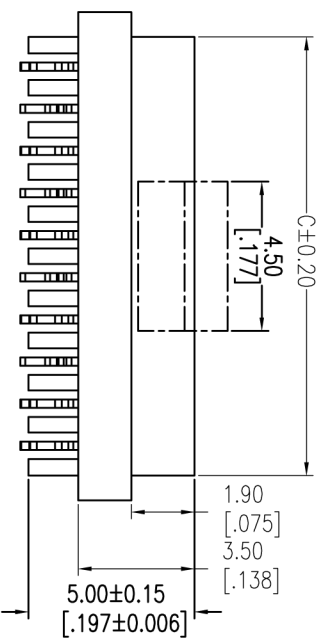
- Current Rating: 1.0AMP
- Contact Resistance: 20mΩ Max
- Withstand Voltage: 500V AC/DC
- Insulation Resistance: 1000MΩ Min
- Operation Temperature: -40°C to +105°C
- Contact Material: Phosphor Bronze
- Contact plating: Sn Over Ni
- Insulator Material: PA46+30%G.F UL94V-0



## Ordering Information

3900-XX FM SN E N T 01

- No. of Pins
- 04P 12P
- 06P 14P
- 08P 16P
- 10P 18P
- 20P
- Contact Plating
- SN=Tim
- Insulator Material
- E=P-PA46
- Packing
- T=Tube
- P=Tube+CAP
- R=Tape&Reel+CAP



Circuit	Part No.	Dimension			Qty /Tube
		A	B	C	
04	3900-04FMSNENT01	7.00	3.81	5.60	82
06	3900-06FMSNENT01	9.54	6.35	8.14	60
08	3900-08FMSNENT01	12.08	8.89	10.68	48
10	3900-10FMSNENT01	14.62	11.43	13.22	39
12	3900-12FMSNENT01	17.16	13.97	15.76	33
14	3900-14FMSNENT01	19.70	16.51	18.30	29
16	3900-16FMSNENT01	22.24	19.05	20.84	26
18	3900-18FMSNENT01	24.78	21.59	23.38	23
20	3900-20FMSNENT01	27.32	24.13	25.92	21

OPERATION SCALE FIT PART NO. SEE TAB

XX ±0.40 JYhuang 2014/05/28

X.XX ±0.25 CHECK DATE

X.XXX ±0.15 APPROVE DATE

Angle ± 3' DIM TOL

CHANGE DIM TOL

**hf** 上海回峰电子科技有限公司  
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REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
A1	2014/05/28	MICRO MATCH--MINI MATCH	△	XX	JYhuang	2014/05/28	mm	A4	SEE TAB
A0	2012/10/11	NEW	---	X.XXX	CHECK	DATE	SIZE	1/1	Mini Match Socket 180° SMT Without Latch
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle	APPROVE	DATE	SHEET	1/1	Customer NO.